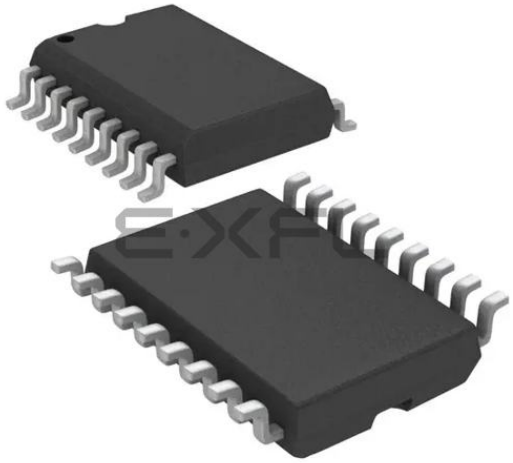

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	16
Program Memory Size	4KB (2K x 16)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf1230-i-so

TABLE 5-4: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices		Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets, WDT Reset, RESET Instruction, Stack Resets	Wake-up via WDT or Interrupt
INDF2	1230	1330	N/A	N/A	N/A
POSTINC2	1230	1330	N/A	N/A	N/A
POSTDEC2	1230	1330	N/A	N/A	N/A
PREINC2	1230	1330	N/A	N/A	N/A
PLUSW2	1230	1330	N/A	N/A	N/A
FSR2H	1230	1330	---- 0000	---- 0000	---- uuuu
FSR2L	1230	1330	xxxx xxxx	uuuu uuuu	uuuu uuuu
STATUS	1230	1330	---x xxxx	---u uuuu	---u uuuu
TMR0H	1230	1330	0000 0000	0000 0000	uuuu uuuu
TMR0L	1230	1330	xxxx xxxx	uuuu uuuu	uuuu uuuu
T0CON	1230	1330	1111 1111	1111 1111	uuuu uuuu
OSCCON	1230	1330	0100 q000	0100 q000	uuuu uuqu
LVDCON	1230	1330	--00 0101	--00 0101	--uu uuuu
WDTCON	1230	1330	---- ---0	---- ---0	---- ---u
RCON(4)	1230	1330	0q-1 11q0	0q-q qquu	uq-u qquu
TMR1H	1230	1330	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1L	1230	1330	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	1230	1330	0000 0000	u0uu uuuu	uuuu uuuu
ADRESH	1230	1330	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADRESL	1230	1330	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	1230	1330	0--- 0000	0--- 0000	u--- uuuu
ADCON1	1230	1330	---0 1111	---0 1111	---u uuuu
ADCON2	1230	1330	0-00 0000	0-00 0000	u-uu uuuu
BAUDCON	1230	1330	01-00 0-00	01-00 0-00	uu-uu u-uu
CVRCON	1230	1330	0-00 0000	0-00 0000	u-uu uuuu
CMCON	1230	1330	000- -000	000- -000	uuu- -uuu
SPBRGH	1230	1330	0000 0000	0000 0000	uuuu uuuu
SPBRG	1230	1330	0000 0000	0000 0000	uuuu uuuu
RCREG	1230	1330	0000 0000	0000 0000	uuuu uuuu
TXREG	1230	1330	0000 0000	0000 0000	uuuu uuuu
TXSTA	1230	1330	0000 0010	0000 0010	uuuu uuuu
RCSTA	1230	1330	0000 000x	0000 000x	uuuu uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

4: See Table 5-3 for Reset value for specific condition.

5: Bits 6 and 7 of PORTA, LATA and TRISA are enabled depending on the oscillator mode selected. When not enabled as PORTA pins, they are disabled and read as '0'.

6: Reset condition of PWMEN bits depends on the PWMPIN Configuration bit of CONFIG3L.

6.1.2.4 Stack Full and Underflow Resets

Device Resets on stack overflow and stack underflow conditions are enabled by setting the STVREN bit in Configuration Register 4L. When STVREN is set, a full or underflow will set the appropriate STKFUL or STKUNF bit and then cause a device Reset. When STVREN is cleared, a full or underflow condition will set the appropriate STKFUL or STKUNF bit but not cause a device Reset. The STKFUL or STKUNF bit is cleared by the user software or a Power-on Reset.

6.1.3 FAST REGISTER STACK

A Fast Register Stack is provided for the STATUS, WREG and BSR registers, to provide a “fast return” option for interrupts. The stack for each register is only one level deep and is neither readable nor writable. It is loaded with the current value of the corresponding register when the processor vectors for an interrupt. All interrupt sources will push values into the Stack registers. The values in the registers are then loaded back into their associated registers if the RETFIE, FAST instruction is used to return from the interrupt.

If both low and high-priority interrupts are enabled, the Stack registers cannot be used reliably to return from low-priority interrupts. If a high-priority interrupt occurs while servicing a low-priority interrupt, the Stack register values stored by the low-priority interrupt will be overwritten. In these cases, users must save the key registers in software during a low-priority interrupt.

If interrupt priority is not used, all interrupts may use the Fast Register Stack for returns from interrupt. If no interrupts are used, the Fast Register Stack can be used to restore the STATUS, WREG and BSR registers at the end of a subroutine call. To use the Fast Register Stack for a subroutine call, a CALL label, FAST instruction must be executed to save the STATUS, WREG and BSR registers to the Fast Register Stack. A RETURN, FAST instruction is then executed to restore these registers from the Fast Register Stack.

Example 6-1 shows a source code example that uses the Fast Register Stack during a subroutine call and return.

EXAMPLE 6-1: FAST REGISTER STACK CODE EXAMPLE

```
CALL  SUB1, FAST    ;STATUS, WREG, BSR
                    ;SAVED IN FAST REGISTER
                    ;STACK
      •
      •

SUB1  •
      •
      RETURN, FAST  ;RESTORE VALUES SAVED
                    ;IN FAST REGISTER STACK
```

6.1.4 LOOK-UP TABLES IN PROGRAM MEMORY

There may be programming situations that require the creation of data structures, or look-up tables, in program memory. For PIC18 devices, look-up tables can be implemented in two ways:

- Computed GOTO
- Table Reads

6.1.4.1 Computed GOTO

A computed GOTO is accomplished by adding an offset to the program counter. An example is shown in Example 6-2.

A look-up table can be formed with an ADDWF PCL instruction and a group of RETLW nn instructions. The W register is loaded with an offset into the table before executing a call to that table. The first instruction of the called routine is the ADDWF PCL instruction. The next instruction executed will be one of the RETLW nn instructions that returns the value ‘nn’ to the calling function.

The offset value (in WREG) specifies the number of bytes that the program counter should advance and should be multiples of 2 (LSb = 0).

In this method, only one data byte may be stored in each instruction location and room on the return address stack is required.

EXAMPLE 6-2: COMPUTED GOTO USING AN OFFSET VALUE

```
        MOVF    OFFSET, W
        CALL    TABLE
ORG     nn00h
TABLE   ADDWF   PCL
        RETLW   nnh
        RETLW   nnh
        RETLW   nnh
        .
        .
        .
```

6.1.4.2 Table Reads and Table Writes

A better method of storing data in program memory allows two bytes of data to be stored in each instruction location.

Look-up table data may be stored two bytes per program word by using table reads and writes. The Table Pointer (TBLPTR) register specifies the byte address and the Table Latch (TABLAT) register contains the data that is read from or written to program memory. Data is transferred to or from program memory one byte at a time.

Table read and table write operations are discussed further in **Section 7.1 “Table Reads and Table Writes”**.

6.2.3 INSTRUCTIONS IN PROGRAM MEMORY

The program memory is addressed in bytes. Instructions are stored as two bytes or four bytes in program memory. The Least Significant Byte of an instruction word is always stored in a program memory location with an even address (LSb = 0). To maintain alignment with instruction boundaries, the PC increments in steps of 2 and the LSb will always read '0' (see **Section 6.1.1 "Program Counter"**).

Figure 6-4 shows an example of how instruction words are stored in the program memory.

The CALL and GOTO instructions have the absolute program memory address embedded into the instruction. Since instructions are always stored on word boundaries, the data contained in the instruction is a word address. The word address is written to PC<20:1>, which accesses the desired byte address in program memory. Instruction #2 in Figure 6-4 shows how the instruction, GOTO 0006h, is encoded in the program memory. Program branch instructions, which encode a relative address offset, operate in the same manner. The offset value stored in a branch instruction represents the number of single-word instructions that the PC will be offset by. **Section 22.0 "Instruction Set Summary"** provides further details of the instruction set.

FIGURE 6-4: INSTRUCTIONS IN PROGRAM MEMORY

			LSB = 1	LSB = 0	Word Address ↓
Program Memory Byte Locations →					000000h
					000002h
					000004h
					000006h
Instruction 1:	MOVLW	055h	0Fh	55h	000008h
Instruction 2:	GOTO	0006h	EFh	03h	00000Ah
			F0h	00h	00000Ch
Instruction 3:	MOVFF	123h, 456h	C1h	23h	00000Eh
			F4h	56h	000010h
					000012h
					000014h

6.2.4 TWO-WORD INSTRUCTIONS

The standard PIC18 instruction set has four two-word instructions: CALL, MOVFF, GOTO and LSFR. In all cases, the second word of the instructions always has '1111' as its four Most Significant bits; the other 12 bits are literal data, usually a data memory address.

The use of '1111' in the 4 MSbs of an instruction specifies a special form of NOP. If the instruction is executed in proper sequence – immediately after the first word – the data in the second word is accessed and used by the instruction sequence. If the first word is skipped for some reason and the second word is executed by itself, a NOP is executed instead. This is necessary for cases when the two-word instruction is preceded by a conditional instruction that changes the PC. Example 6-4 shows how this works.

Note:	See **Section 6.6 "PIC18 Instruction Execution and the Extended Instruction Set"** for information on two-word instructions in the extended instruction set.

EXAMPLE 6-4: TWO-WORD INSTRUCTIONS

CASE 1:

Object Code	Source Code		
0110 0110 0000 0000	TSTFSZ	REG1	; is RAM location 0?
1100 0001 0010 0011	MOVFF	REG1, REG2	; No, skip this word
1111 0100 0101 0110			; Execute this word as a NOP
0010 0100 0000 0000	ADDWF	REG3	; continue code

CASE 2:

Object Code	Source Code		
0110 0110 0000 0000	TSTFSZ	REG1	; is RAM location 0?
1100 0001 0010 0011	MOVFF	REG1, REG2	; Yes, execute this word
1111 0100 0101 0110			; 2nd word of instruction
0010 0100 0000 0000	ADDWF	REG3	; continue code

7.2.2 TABLAT – TABLE LATCH REGISTER

The Table Latch (TABLAT) is an 8-bit register mapped into the SFR space. The Table Latch register is used to hold 8-bit data during data transfers between program memory and data RAM.

7.2.3 TBLPTR – TABLE POINTER REGISTER

The Table Pointer (TBLPTR) register addresses a byte within the program memory. The TBLPTR is comprised of three SFR registers: Table Pointer Upper Byte, Table Pointer High Byte and Table Pointer Low Byte (TBLPTRU:TBLPTRH:TBLPTRL). These three registers join to form a 22-bit wide pointer. The low-order 21 bits allow the device to address up to 2 Mbytes of program memory space. The 22nd bit allows access to the device ID, the user ID and the Configuration bits.

The Table Pointer register, TBLPTR, is used by the TBLRD and TBLWT instructions. These instructions can update the TBLPTR in one of four ways based on the table operation. These operations are shown in Table 7-1. These operations on the TBLPTR only affect the low-order 21 bits.

7.2.4 TABLE POINTER BOUNDARIES

TBLPTR is used in reads, writes and erases of the Flash program memory.

When a TBLRD is executed, all 22 bits of the TBLPTR determine which byte is read from program memory into TABLAT.

When the timed write to program memory begins (via the WR bit), the 19 MSbs of the TBLPTR (TBLPTR<21:3>) determine which program memory block of 8 bytes is written to. The Table Pointer register's three LSBs (TBLPTR<2:0>) are ignored. For more detail, see **Section 7.5 "Writing to Flash Program Memory"**.

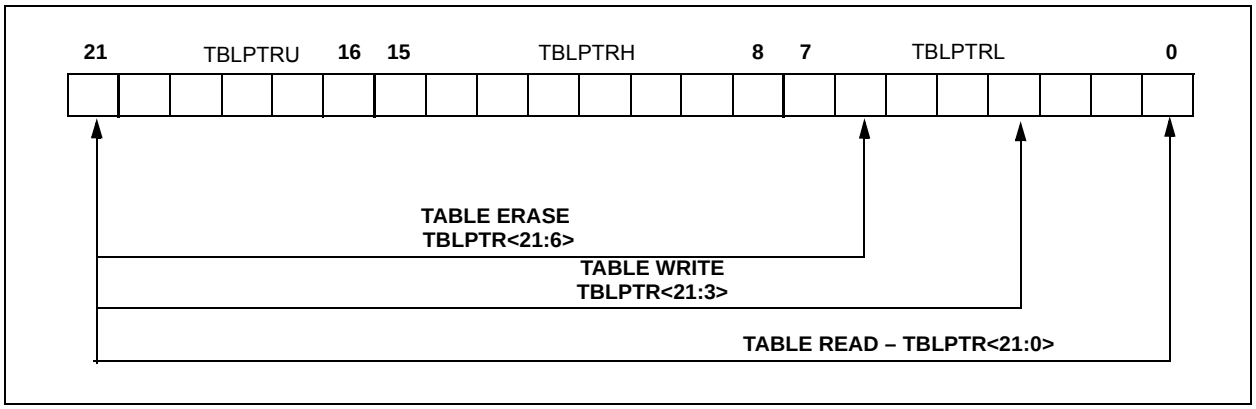
When an erase of program memory is executed, the 16 MSbs of the Table Pointer register (TBLPTR<21:6>) point to the 64-byte block that will be erased. The Least Significant bits (TBLPTR<5:0>) are ignored.

Figure 7-3 describes the relevant boundaries of TBLPTR based on Flash program memory operations.

TABLE 7-1: TABLE POINTER OPERATIONS WITH TBLRD AND TBLWT INSTRUCTIONS

Example	Operation on Table Pointer
TBLRD* TBLWT*	TBLPTR is not modified
TBLRD*+ TBLWT*+	TBLPTR is incremented after the read/write
TBLRD*- TBLWT*-	TBLPTR is decremented after the read/write
TBLRD+* TBLWT+*	TBLPTR is incremented before the read/write

FIGURE 7-3: TABLE POINTER BOUNDARIES BASED ON OPERATION



EXAMPLE 7-3: WRITING TO FLASH PROGRAM MEMORY (CONTINUED)

```
PROGRAM_MEMORY
                BSF     EECON1, EEPGD           ; point to Flash program memory
                BCF     EECON1, CFGS            ; access Flash program memory
                BSF     EECON1, WREN            ; enable write to memory
                BCF     INTCON, GIE             ; disable interrupts
                MOVLW   55h
    Required    MOVWF   EECON2                  ; write 55h
    Sequence    MOVLW   0AAh
                MOVWF   EECON2                  ; write 0AAh
                BSF     EECON1, WR              ; start program (CPU stall)
                BSF     INTCON, GIE             ; re-enable interrupts
                BCF     EECON1, WREN            ; disable write to memory
```

7.5.2 WRITE VERIFY

Depending on the application, good programming practice may dictate that the value written to the memory should be verified against the original value. This should be used in applications where excessive writes can stress bits near the specification limit.

7.5.3 UNEXPECTED TERMINATION OF WRITE OPERATION

If a write is terminated by an unplanned event, such as loss of power or an unexpected Reset, the memory location just programmed should be verified and reprogrammed, if needed. If the write operation is interrupted by a $\overline{\text{MCLR}}$ Reset or a WDT Time-out Reset during normal operation, the user can check the WRERR bit and rewrite the location(s) as needed.

7.5.4 PROTECTION AGAINST SPURIOUS WRITES

To protect against spurious writes to Flash program memory, the write initiate sequence must also be followed. See **Section 20.0 "Special Features of the CPU"** for more detail.

7.6 Flash Program Operation During Code Protection

See **Section 20.5 "Program Verification and Code Protection"** for details on code protection of Flash program memory.

TABLE 7-2: REGISTERS ASSOCIATED WITH PROGRAM FLASH MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
TBLPTRU	—	—	bit 21	Program Memory Table Pointer Upper Byte (TBLPTR<20:16>)					47
TBPLTRH	Program Memory Table Pointer High Byte (TBLPTR<15:8>)								47
TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR<7:0>)								47
TABLAT	Program Memory Table Latch								47
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	47
EECON2	EEPROM Control Register 2 (not a physical register)								49
EECON1	EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD	49
IPR2	OSCFIP	—	—	EEIP	—	LVDIP	—	—	49
PIR2	OSCFIF	—	—	EEIF	—	LVDIF	—	—	49
PIE2	OSCFIE	—	—	EEIE	—	LVDIE	—	—	49

Legend: — = unimplemented, read as '0'. Shaded cells are not used during Flash/EEPROM access.

14.0 POWER CONTROL PWM MODULE

The Power Control PWM module simplifies the task of generating multiple, synchronized Pulse-Width Modulated (PWM) outputs for use in the control of motor controllers and power conversion applications. In particular, the following power and motion control applications are supported by the PWM module:

- Three-Phase and Single-Phase AC Induction Motors
- Switched Reluctance Motors
- Brushless DC (BLDC) Motors
- Uninterruptible Power Supplies (UPS)
- Multiple DC Brush Motors

The PWM module has the following features:

- Up to six PWM I/O pins with three duty cycle generators. Pins can be paired to acquire a complete half-bridge control.
- Up to 14-bit resolution, depending upon the PWM period.
- “On-the-fly” PWM frequency changes.
- Edge and Center-Aligned Output modes.
- Single-Pulse Generation mode.
- Programmable dead-time control between paired PWMs.
- Interrupt support for asymmetrical updates in Center-Aligned mode.
- Output override for Electrically Commutated Motor (ECM) operation; for example, BLDC.
- Special Event Trigger comparator for triggering A/D conversion.
- PWM outputs disable feature sets PWM outputs to their inactive state when in Debug mode.

The Power Control PWM module supports three PWM generators and six output channels on PIC18F1230/1330 devices. A simplified block diagram of the module is shown in Figure 14-1. Figure 14-2 and Figure 14-3 show how the module hardware is configured for each PWM output pair for the Complementary and Independent Output modes.

Each functional unit of the PWM module will be discussed in subsequent sections.

REGISTER 14-3: PWMCON0: PWM CONTROL REGISTER 0

U-0	R/W-1(1)	R/W-1(1)	R/W-1(1)	U-0	R/W-0	R/W-0	R/W-0
—	PWMEN2	PWMEN1	PWMEN0	—	PMOD2	PMOD1	PMOD0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **PWMEN2:PWMEN0:** PWM Module Enable bits(1)

111 = All odd PWM I/O pins enabled for PWM output
110 = PWM1, PWM3 pins enabled for PWM output
10x = All PWM I/O pins enabled for PWM output
011 = PWM0, PWM1, PWM2 and PWM3 I/O pins enabled for PWM output
010 = PWM0 and PWM1 pins enabled for PWM output
001 = PWM1 pin is enabled for PWM output
000 = PWM module disabled; all PWM I/O pins are general purpose I/O

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **PMOD2:PMOD0:** PWM Output Pair Mode bits

For PMOD0:
1 = PWM I/O pin pair (PWM0, PWM1) is in the Independent mode
0 = PWM I/O pin pair (PWM0, PWM1) is in the Complementary mode

For PMOD1:
1 = PWM I/O pin pair (PWM2, PWM3) is in the Independent mode
0 = PWM I/O pin pair (PWM2, PWM3) is in the Complementary mode

For PMOD2:
1 = PWM I/O pin pair (PWM4, PWM5) is in the Independent mode
0 = PWM I/O pin pair (PWM4, PWM5) is in the Complementary mode

Note 1: Reset condition of PWMEN bits depends on the PWMPIN Configuration bit of CONFIG3L.

15.1.3 AUTO-BAUD RATE DETECT

The Enhanced USART module supports the automatic detection and calibration of baud rate. This feature is active only in Asynchronous mode and while the WUE bit is clear.

The automatic baud rate measurement sequence (Figure 15-1) begins whenever a Start bit is received and the ABDEN bit is set. The calculation is self-averaging.

In the Auto-Baud Rate Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. In ABD mode, the internal Baud Rate Generator is used as a counter to time the bit period of the incoming serial byte stream.

Once the ABDEN bit is set, the state machine will clear the BRG and look for a Start bit. The Auto-Baud Rate Detect must receive a byte with the value 55h (ASCII "U", which is also the LIN/J2602 bus Sync character) in order to calculate the proper bit rate. The measurement is taken over both a low and a high bit time in order to minimize any effects caused by asymmetry of the incoming signal. After a Start bit, the SPBRG begins counting up, using the preselected clock source on the first rising edge of RX. After eight bits on the RX pin or the fifth rising edge, an accumulated value totalling the proper BRG period is left in the SPBRGH:SPBRG register pair. Once the 5th edge is seen (this should correspond to the Stop bit), the ABDEN bit is automatically cleared.

If a rollover of the BRG occurs (an overflow from FFFFh to 0000h), the event is trapped by the ABDOVF status bit (BAUDCON<7>). It is set in hardware by BRG rollovers and can be set or cleared by the user in software. ABD mode remains active after rollover events and the ABDEN bit remains set (Figure 15-2).

While calibrating the baud rate period, the BRG registers are clocked at 1/8th the preconfigured clock rate. Note that the BRG clock can be configured by the BRG16 and BRGH bits. The BRG16 bit must be set to use both SPBRG1 and SPBRGH1 as a 16-bit counter. This allows the user to verify that no carry occurred for 8-bit modes by checking for 00h in the SPBRGH register. Refer to Table 15-4 for counter clock rates to the BRG.

While the ABD sequence takes place, the EUSART state machine is held in Idle. The RCIF interrupt is set once the fifth rising edge on RX is detected. The value in the RCREG needs to be read to clear the RCIF interrupt. The contents of RCREG should be discarded.

Note 1: If the WUE bit is set with the ABDEN bit, Auto-Baud Rate Detection will occur on the byte *following* the Break character.

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible due to bit error rates. Overall system timing and communication baud rates must be taken into consideration when using the Auto-Baud Rate Detection feature.

3: To maximize baud rate range, it is recommended to set the BRG16 bit if the auto-baud feature is used.

TABLE 15-4: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Counter Clock
0	0	FOSC/512
0	1	FOSC/128
1	0	FOSC/128
1	1	FOSC/32

15.1.3.1 ABD and EUSART Transmission

Since the BRG clock is reversed during ABD acquisition, the EUSART transmitter cannot be used during ABD. This means that whenever the ABDEN bit is set, TXREG cannot be written to. Users should also ensure that ABDEN does not become set during a transmit sequence. Failing to do this may result in unpredictable EUSART operation.

16.1 Triggering A/D Conversions

The A/D conversion can be triggered by setting the GO/DONE bit. This bit can either be set manually by the programmer or by setting the SEVTEN bit of ADCON0. When the SEVTEN bit is set, the Special Event Trigger from the Power Control PWM module triggers the A/D conversion. For more information, see **Section 14.14 "PWM Special Event Trigger"**.

16.2 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 16-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 2.5 kΩ**. After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

To calculate the minimum acquisition time, Equation 16-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Example 16-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the following application system assumptions:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	≤	1/2 LSb
VDD	=	5V → RSS = 2 kΩ
Temperature	=	85°C (system max.)

EQUATION 16-1: ACQUISITION TIME

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Holding Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$

EQUATION 16-2: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/2048)) \cdot (1 - e^{(-T_C/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$$
or
$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/2048)$$

EQUATION 16-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$$T_{ACQ} = T_{AMP} + T_C + T_{COFF}$$
$$T_{AMP} = 0.2\ \mu s$$
$$T_{COFF} = (\text{Temp} - 25°C)(0.02\ \mu s/°C)$$
$$(85°C - 25°C)(0.02\ \mu s/°C)$$
$$1.2\ \mu s$$

Temperature coefficient is only required for temperatures > 25°C. Below 25°C, T_{COFF} = 0 ms.

$$T_C = -(C_{HOLD})(R_{IC} + R_{SS} + R_S) \ln(1/2047)$$
$$-(25\ pF)(1\ k\Omega + 2\ k\Omega + 2.5\ k\Omega) \ln(0.0004883)$$
$$1.05\ \mu s$$
$$T_{ACQ} = 0.2\ \mu s + 1\ \mu s + 1.2\ \mu s$$
$$2.4\ \mu s$$

19.0 LOW-VOLTAGE DETECT (LVD)

PIC18F1230/1330 devices have a Low-Voltage Detect module (LVD). This is a programmable circuit that allows the user to specify the device voltage trip point. If the device experiences an excursion past the trip point, an interrupt flag is set. If the interrupt is enabled, the program execution will branch to the interrupt vector address and the software can then respond to the interrupt.

The Low-Voltage Detect Control register (Register 19-1) completely controls the operation of the LVD module. This allows the circuitry to be "turned off" by the user under software control, which minimizes the current consumption for the device.

The block diagram for the LVD module is shown in Figure 19-1.

REGISTER 19-1: LVDCON: LOW-VOLTAGE DETECT CONTROL REGISTER

U-0	U-0	R-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-1
—	—	IRVST	LVDEN	LVDL3(1)	LVDL2(1)	LVDL1(1)	LVDL0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
- 1 = Indicates that the voltage detect logic will generate the interrupt flag at the specified voltage trip point
- 0 = Indicates that the voltage detect logic will not generate the interrupt flag at the specified voltage trip point and the LVD interrupt should not be enabled

bit 4 **LVDEN:** Low-Voltage Detect Power Enable bit
- 1 = LVD enabled
- 0 = LVD disabled

bit 3-0 **LVDL3:LVDL0:** Voltage Detection Limit bits(1)
- 1111 = Reserved
- 1110 = Maximum setting
- .
- .
- .
- 0000 = Minimum setting

Note 1: See Table 23-4 in **Section 23.0 "Electrical Characteristics"** for the specifications.

REGISTER 20-1: CONFIG1H: CONFIGURATION REGISTER 1 HIGH (BYTE ADDRESS 300001h)

R/P-0	R/P-0	U-0	U-0	R/P-0	R/P-1	R/P-1	R/P-1
IESO	FCMEN	—	—	FOSC3	FOSC2	FOSC1	FOSC0
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7 **IESO:** Internal/External Oscillator Switchover bit
1 = Oscillator Switchover mode enabled
0 = Oscillator Switchover mode disabled

bit 6 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor enabled
0 = Fail-Safe Clock Monitor disabled

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **FOSC3:FOSC0:** Oscillator Selection bits
11xx = External RC oscillator, CLKO function on RA6
101x = External RC oscillator, CLKO function on RA6
1001 = Internal oscillator block, CLKO function on RA6, port function on RA7
1000 = Internal oscillator block, port function on RA6 and RA7
0111 = External RC oscillator, port function on RA6
0110 = HS oscillator, PLL enabled (Clock Frequency = 4 x FOSC1)
0101 = EC oscillator, port function on RA6
0100 = EC oscillator, CLKO function on RA6
0011 = External RC oscillator, CLKO function on RA6
0010 = HS oscillator
0001 = XT oscillator
0000 = LP oscillator

TABLE 22-1: OPCODE FIELD DESCRIPTIONS

Field	Description
a	RAM access bit a = 0: RAM location in Access RAM (BSR register is ignored) a = 1: RAM bank is specified by BSR register
bbb	Bit address within an 8-bit file register (0 to 7).
BSR	Bank Select Register. Used to select the current RAM bank.
C, DC, Z, OV, N	ALU Status bits: **C**arry, **D**igit **C**arry, **Z**ero, **Ov**erflow, **N**egative.
d	Destination select bit d = 0: store result in WREG d = 1: store result in file register f
dest	Destination: either the WREG register or the specified register file location.
f	8-bit Register file address (00h to FFh) or 2-bit FSR designator (0h to 3h).
f_s	12-bit Register file address (000h to FFFh). This is the source address.
f_d	12-bit Register file address (000h to FFFh). This is the destination address.
GIE	Global Interrupt Enable bit.
k	Literal field, constant data or label (may be either an 8-bit, 12-bit or a 20-bit value).
label	Label name.
mm * *+ *- +*	The mode of the TBLPTR register for the table read and table write instructions. Only used with table read and table write instructions: No change to register (such as TBLPTR with table reads and writes) Post-Increment register (such as TBLPTR with table reads and writes) Post-Decrement register (such as TBLPTR with table reads and writes) Pre-Increment register (such as TBLPTR with table reads and writes)
n	The relative address (2's complement number) for relative branch instructions or the direct address for Call/Branch and Return instructions.
PC	Program Counter.
PCL	Program Counter Low Byte.
PCH	Program Counter High Byte.
PCLATH	Program Counter High Byte Latch.
PCLATU	Program Counter Upper Byte Latch.
$\overline{PD}$	Power-Down bit.
PRODH	Product of Multiply High Byte.
PRODL	Product of Multiply Low Byte.
s	Fast Call/Return mode select bit s = 0: do not update into/from shadow registers s = 1: certain registers loaded into/from shadow registers (Fast mode)
TBLPTR	21-bit Table Pointer (points to a program memory location).
TABLAT	8-bit Table Latch.
$\overline{TO}$	Time-out bit.
TOS	Top-of-Stack.
u	Unused or unchanged.
WDT	Watchdog Timer.
WREG	Working register (accumulator).
x	Don't care ('0' or '1'). The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
z_s	7-bit offset value for indirect addressing of register files (source).
z_d	7-bit offset value for indirect addressing of register files (destination).
{ }	Optional argument.
[text]	Indicates an indexed address.
(text)	The contents of text.
[expr]<n>	Specifies bit n of the register indicated by the pointer expr.
→	Assigned to.
< >	Register bit field.
∈	In the set of.
italics	User-defined term (font is Courier New).

SUBLW **Subtract W from Literal**

Syntax: SUBLW k

Operands: $0 \le k \le 255$

Operation: $k - (W) \rightarrow W$

Status Affected: N, OV, C, DC, Z

Encoding:

0000	1000	kkkk	kkkk

Description: W is subtracted from the eight-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example 1: SUBLW 02h

Before Instruction
W = 01h
C = ?
After Instruction
W = 01h
C = 1 ; result is positive
Z = 0
N = 0

Example 2: SUBLW 02h

Before Instruction
W = 02h
C = ?
After Instruction
W = 00h
C = 1 ; result is zero
Z = 1
N = 0

Example 3: SUBLW 02h

Before Instruction
W = 03h
C = ?
After Instruction
W = FFh ; (2's complement)
C = 0 ; result is negative
Z = 0
N = 1

SUBWF **Subtract W from f**

Syntax: SUBWF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: $(f) - (W) \rightarrow$ dest

Status Affected: N, OV, C, DC, Z

Encoding:

0101	11da	ffff	ffff

Description: Subtract W from register 'f' (2's complement method). If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f'. If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank. If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 22.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1: SUBWF REG, 1, 0

Before Instruction
REG = 3
W = 2
C = ?
After Instruction
REG = 1
W = 2
C = 1 ; result is positive
Z = 0
N = 0

Example 2: SUBWF REG, 0, 0

Before Instruction
REG = 2
W = 2
C = ?
After Instruction
REG = 2
W = 0
C = 1 ; result is zero
Z = 1
N = 0

Example 3: SUBWF REG, 1, 0

Before Instruction
REG = 1
W = 2
C = ?
After Instruction
REG = FFh ;(2's complement)
W = 2
C = 0 ; result is negative
Z = 0
N = 1

22.2.2 EXTENDED INSTRUCTION SET

ADDFSR **Add Literal to FSR**

Syntax: ADDFSR f, k

Operands: $0 \le k \le 63$
$f \in [0, 1, 2]$

Operation: FSR(f) + k → FSR(f)

Status Affected: None

Encoding:

1110	1000	ffkk	kkkk

Description: The 6-bit literal 'k' is added to the contents of the FSR specified by 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to FSR

Example: ADDFSR 2, 23h

Before Instruction
FSR2 = 03FFh
After Instruction
FSR2 = 0422h

ADDULNK **Add Literal to FSR2 and Return**

Syntax: ADDULNK k

Operands: $0 \le k \le 63$

Operation: FSR2 + k → FSR2,
(TOS) → PC

Status Affected: None

Encoding:

1110	1000	11kk	kkkk

Description: The 6-bit literal 'k' is added to the contents of FSR2. A RETURN is then executed by loading the PC with the TOS.
The instruction takes two cycles to execute; a NOP is performed during the second cycle.
This may be thought of as a special case of the ADDFSR instruction, where f = 3 (binary '11'); it operates only on FSR2.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to FSR
No Operation	No Operation	No Operation	No Operation

Example: ADDULNK 23h

Before Instruction
FSR2 = 03FFh
PC = 0100h
After Instruction
FSR2 = 0422h
PC = (TOS)

Note: All PIC18 instructions may take an optional label argument preceding the instruction mnemonic for use in symbolic addressing. If a label is used, the instruction syntax then becomes: {label} instruction argument(s).

23.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
$Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}$/V_{PP}/RA5/$\overline{FLTA}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$/V_{PP}/RA5/$\overline{FLTA}$ pin, rather than pulling this pin directly to V_{SS}.

† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

23.2 DC Characteristics: Power-Down and Supply Current PIC18F1230/1330 (Industrial) PIC18LF1230/1330 (Industrial) (Continued)

PIC18LF1230/1330 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F1230/1330 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Supply Current (IDD)(2)						
	PIC18LF1230/1330	0.8	1.83	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**RC_RUN** mode, INTOSC source)
		0.8	1.83	mA	+25°C		
		0.8	1.83	mA	+85°C		
	PIC18LF1230/1330	1.3	2.93	mA	-40°C	VDD = 3.0V	
		1.3	2.93	mA	+25°C		
		1.3	2.93	mA	+85°C		
	All devices	2.5	4.73	mA	-40°C	VDD = 5.0V	
		2.5	4.73	mA	+25°C		
		2.5	4.73	mA	+85°C		
	Extended devices only	2.5	10.0	mA	+125°C		
	PIC18LF1230/1330	2.9	7.6	µA	-40°C	VDD = 2.0V	FOSC = 31 kHz (**RC_IDLE** mode, INTRC source)
		3.1	7.6	µA	+25°C		
		3.6	10.6	µA	+85°C		
	PIC18LF1230/1330	4.5	10.6	µA	-40°C	VDD = 3.0V	
		4.8	10.6	µA	+25°C		
		5.8	14.6	µA	+85°C		
	All devices	9.2	15.6	µA	-40°C	VDD = 5.0V	
		9.8	15.6	µA	+25°C		
		11.4	35.6	µA	+85°C		
	Extended devices only	21	179	µA	+125°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
MCLR = VDD; WDT enabled/disabled as specified.

3: Low-power Timer1 oscillator selected.

4: BOR and LVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

23.2 DC Characteristics: Power-Down and Supply Current PIC18F1230/1330 (Industrial) PIC18LF1230/1330 (Industrial) (Continued)

PIC18LF1230/1330 (Industrial)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC18F1230/1330 (Industrial, Extended)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
	Supply Current (IDD)(2)						
	PIC18LF1230/1330	165	347	µA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**RC_IDLE** mode, INTOSC source)
		175	347	µA	+25°C		
		190	347	µA	+85°C		
	PIC18LF1230/1330	250	497	µA	-40°C	VDD = 3.0V	
		270	497	µA	+25°C		
		290	497	µA	+85°C		
	All devices	500	930	µA	-40°C	VDD = 5.0V	
		520	930	µA	+25°C		
		550	930	µA	+85°C		
	Extended devices only	0.6	2.9	mA	+125°C		
	PIC18LF1230/1330	340	497	µA	-40°C	VDD = 2.0V	FOSC = 4 MHz (**RC_IDLE** mode, INTOSC source)
		350	497	µA	+25°C		
		360	497	µA	+85°C		
	PIC18LF1230/1330	520	830	µA	-40°C	VDD = 3.0V	
		540	830	µA	+25°C		
		580	830	µA	+85°C		
	All devices	1.0	1.33	mA	-40°C	VDD = 5.0V	
		1.1	1.33	mA	+25°C		
		1.1	1.33	mA	+85°C		
	Extended devices only	1.1	5.0	mA	+125°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
MCLR = VDD; WDT enabled/disabled as specified.

3: Low-power Timer1 oscillator selected.

4: BOR and LVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

23.2 DC Characteristics: Power-Down and Supply Current PIC18F1230/1330 (Industrial) PIC18LF1230/1330 (Industrial) (Continued)

PIC18LF1230/1330 (Industrial)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
PIC18F1230/1330 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**		
	Module Differential Currents (ΔIWDT, ΔIBOR, ΔILVD, ΔIOSCB, ΔIAD)						
D026 (ΔIAD)	**A/D Converter**	1.0	1.6	μA	-40°C to +85°C	VDD = 2.0V	A/D on, not converting
		1.0	1.6	μA	-40°C to +85°C	VDD = 3.0V	
		1.0	1.6	μA	-40°C to +85°C	VDD = 5.0V	
		2.0	7.6	μA	-40°C to +125°C		

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
MCLR = VDD; WDT enabled/disabled as specified.

3: Low-power Timer1 oscillator selected.

4: BOR and LVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

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